

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-31 (previously canceled)

Claim 32 (canceled)

Claim 33 (canceled)

Claim 34 (currently amended): An optoelectronic transceiver subassembly for connecting a set of photoactive components with a set of optical fibers supported in an optical ferrule having at least one alignment hole, said transceiver subassembly comprising:

a silicon substrate carrier including at least one alignment aperture extending through the silicon substrate carrier and fabricated on said silicon substrate carrier using photolithography techniques;

an optoelectronic device comprising said set of photoactive components which is precisely mounted on said silicon substrate carrier with reference to said at least one alignment aperture;

at least one guide pin mounted so as to extend through said at least one alignment aperture and mate with said at least one alignment hole in said optical ferrule for aligning said silicon substrate carrier with said optical ferrule and said set of photoactive components with said set of optical fibers; and

a support block attached to said silicon substrate carrier and including at least one support passage for securely supporting said at least one guide pin in alignment with said silicon substrate carrier, and wherein

said silicon substrate carrier also includes at least one alignment mark for use in mounting said optoelectronic device, and wherein

~~The transceiver assembly of claim 33, wherein:~~

said silicon substrate carrier also includes a transparent film layer, on which said at least one alignment mark is deposited, and a window section over which said optoelectronic device is mounted.

Claim 35 (original): The transceiver assembly of claim 34, further including:

a set of metal traces deposited as a grid on said transparent film layer for use in suppressing EMI emissions.

Claims 36-50 (previously canceled)